

Customer No.: 31561  
Application No.: 10/605,602  
Docket NO.: 10233-US-PA

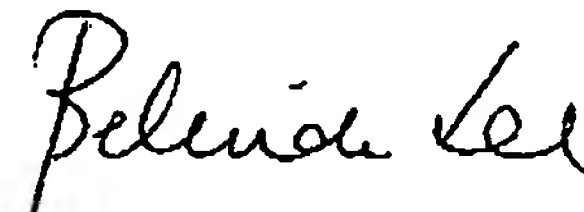
REMARKS

In response to the Office Action, mailed on February 18, 2005, a complete listing of all of the claims is presented herewith. Applicant would like to elect Group I, claims 1-8, drawn to a method of bonding a heat sink to a chip package, classified in class 156, subclass 292. Please cancel Group II, claims 9-20, drawn to a heat sink and a chip package structure, classified in class 257, subclass 678, without waiver, prejudice or disclaimer.

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date: *March 18, 2005*

Respectfully submitted,



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